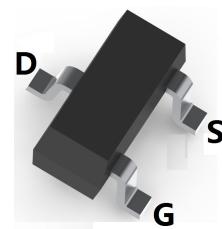
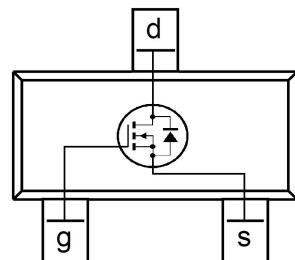


MOSFET (N-CHANNEL)
FEATURES

- $V_{DS}=20V$, $I_D=6.3A$, $R_{DS(ON)}<21m\Omega$ @ $V_{GS}=4.5V$
- Fast switching
- Ultra Low On-Resistance
- Surface Mount device


MECHANICAL DATA

- Case: SOT-23
- Case Material: Molded Plastic. UL flammability
- Classification Rating: 94V-0
- Weight: 0.008 grams (approximate)

SOT-23

MAXIMUM RATINGS ($T_A = 25^\circ C$ unless otherwise noted)

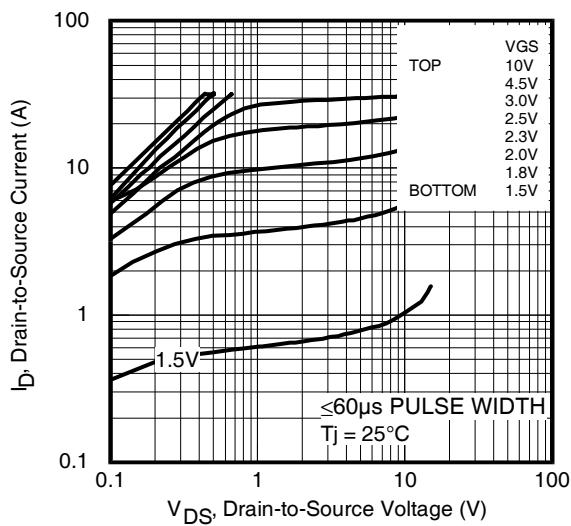
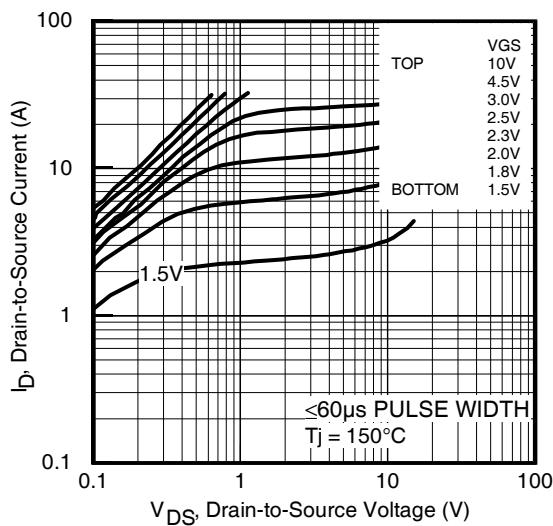
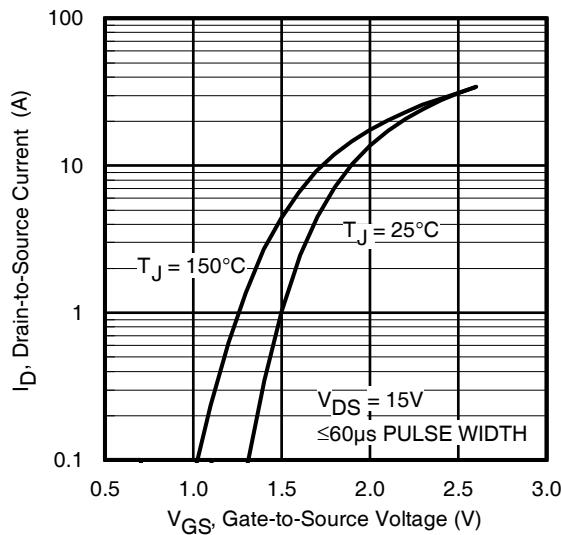
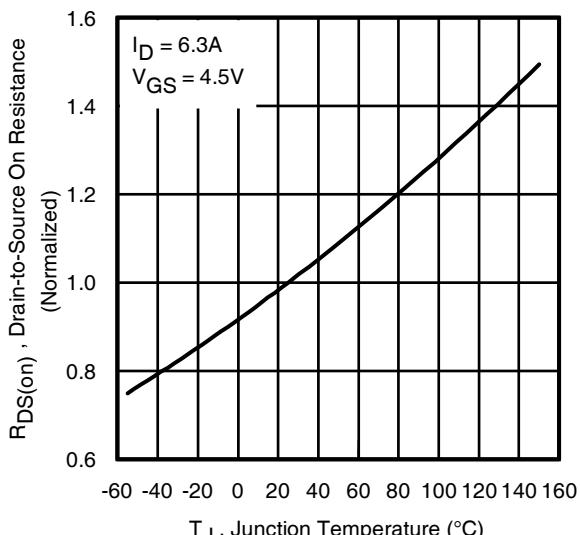
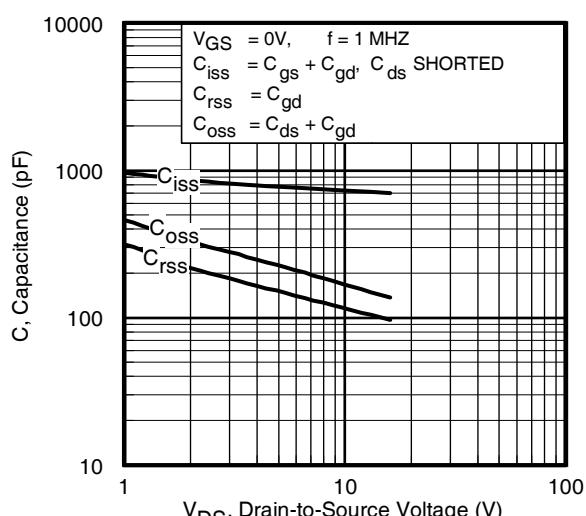
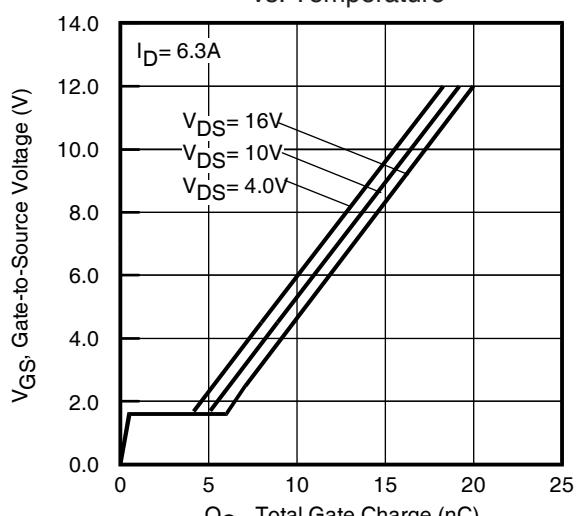
Parameter		Symbol	Value		Unit
Drain-source voltage		V_{DS}	20		V
Gate-source voltage		V_{GS}	+12		V
Continuous drain current	$T_A=25^\circ C$	I_D	6.3		A
	$T_A=70^\circ C$		5.1		
Pulsed drain current (Note 1)		I_{DM}	32		A
Power dissipation	$T_A=25^\circ C$	P_D	1.3		W
	$T_A=70^\circ C$		0.8		
Linear Derating Factor			0.01		W/ $^\circ C$
Thermal resistance from Junction to ambient		R_{QJA}^*	100		$^\circ C/W$
Storage and Junction temperature		T_J, T_{STG}	-55 ~ +150		$^\circ C$

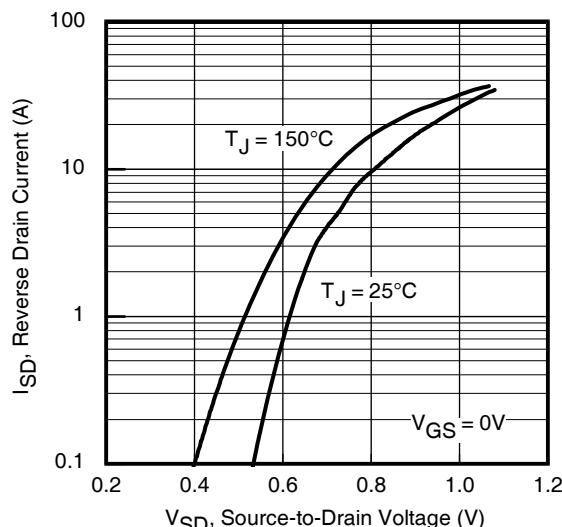
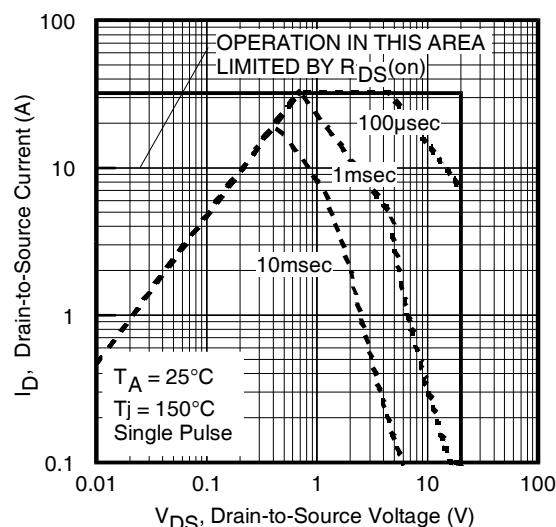
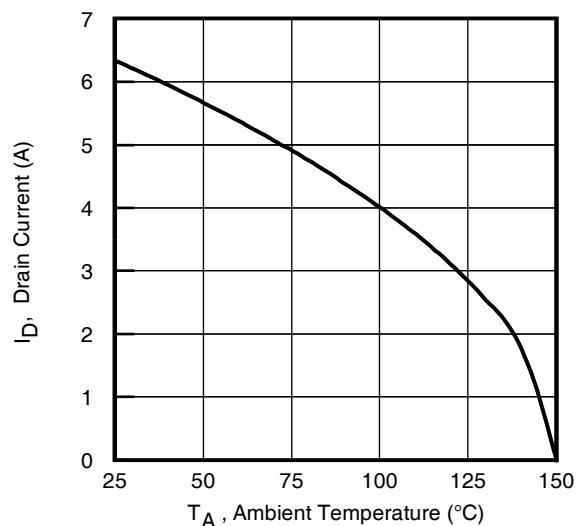
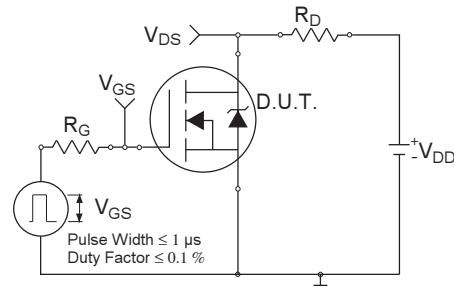
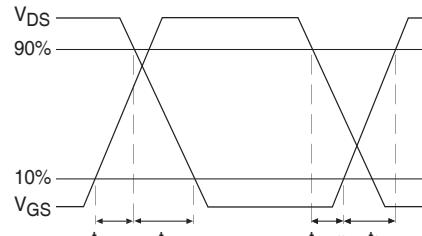
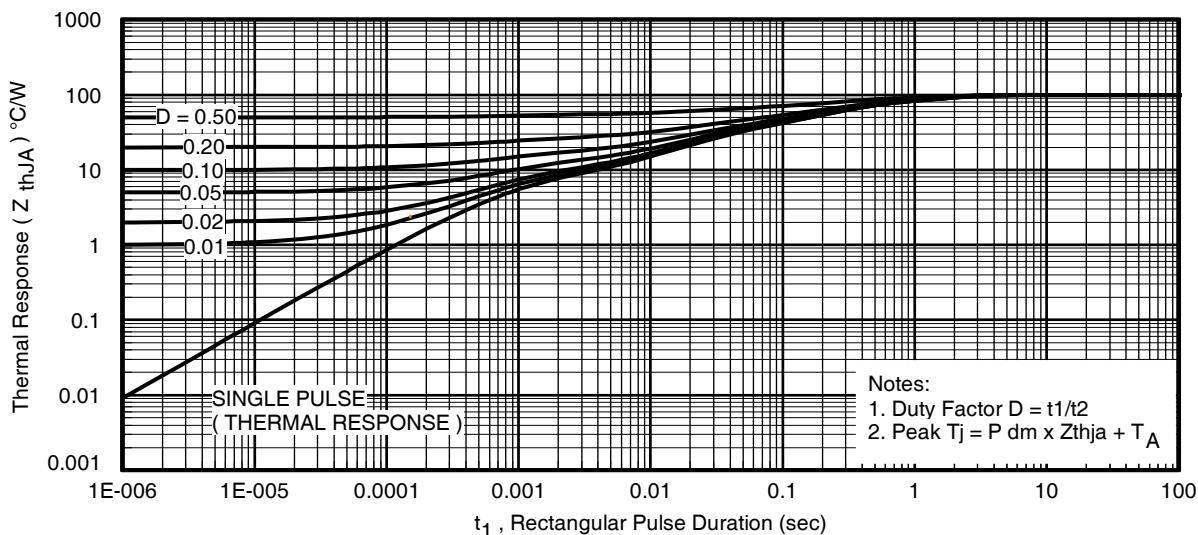
*Surface mounted on 1 in square Cu board

ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ C$ unless otherwise specified)

Parameter	Symbol	Min	Typ	Max	Unit	Conditions
Drain-Source breakdown voltage	$V_{(BR)DSS}$	20			V	$V_{GS}=0V, I_D=250\mu A$
Zero gate voltage drain current	I_{BS}		1		μA	$V_{DS}=16V, V_{GS}=0V$
			150			$V_{DS}=16V, V_{GS}=0V, T_j=125^\circ C$
Gate-body leakage current	I_{GSS}			± 100	nA	$V_{DS}=0V, V_{GS}=+12V$
Gate-threshold voltage (note 1)	$V_{GS(th)}$	0.5	0.9	1.1	V	$V_{DS}=V_{GS}, I_D=10\mu A$
Drain-source on-resistance(note 1)	$R_{DS(ON)}$		16	21	$m\Omega$	$V_{GS}=4.5V, I_D=6.3A$
			22	27	$m\Omega$	$V_{GS}=2.5V, I_D=5.1A$
Internal Gate Resistance	R_G		1.7		Ω	
Forward transconductance(note 1)	g_{FS}	17			S	$V_{DS}=10V, I_D=6.3A$
Input capacitance	C_{iss}	700			pF	
Output capacitance	C_{oss}	140			pF	$V_{DS}=16V, V_{GS}=0V, f=1MHz$
Reverse transfer capacitance	C_{rss}	98			pF	
Turn-on delay time	$t_{d(on)}$	4.9			nS	
Turn-on rise time	t_r	7.5			nS	
Turn-off delay time	$t_{d(off)}$	19			nS	
Turn-off fall time	t_f	12			nS	
Total gate charge	Q_g	8.9			nC	
Gate-source charge	Q_{gs}	0.68			nC	
Gate-drain charge	Q_{gd}	4.4			nC	
Diode forward current(Body Diode)	I_s			1.3	A	integral reverse p-n junction diode
Pulsed Source Current(Body Diode)	I_{SM}			32	A	
Diode forward voltage (note 1)	V_{SD}			1.2	V	$I_s=6.3A, V_{GS}=0V, T_j=25^\circ C$
Reverse Recovery Time	t_{rr}	12	18		nS	$T_j=25^\circ C, V_R=15V, I_F=1.3A, di/dt=100A/\mu s$
Reverse Recovery Charge	Q_{rr}		5.1	7.7	nC	

Note:1. Pulse test ; Pulse width $\leq 400\mu s$, Duty cycle $\leq 2\%$.

MOSFET (N-CHANNEL)
Typical Characteristics

Fig 1. Typical Output Characteristics

Fig 2. Typical Output Characteristics

Fig 3. Typical Transfer Characteristics

Fig 4. Normalized On-Resistance vs. Temperature

Fig 5. Typical Capacitance vs. Drain-to-Source Voltage

Fig 6. Typical Gate Charge vs. Gate-to-Source Voltage

MOSFET (N-CHANNEL)

Fig 7. Typical Source-Drain Diode Forward Voltage

Fig 8. Maximum Safe Operating Area

Fig 9. Maximum Drain Current vs. Ambient Temperature

Fig 10a. Switching Time Test Circuit

Fig 10b. Switching Time Waveforms

Fig 11. Typical Effective Transient Thermal Impedance, Junction-to-Ambient

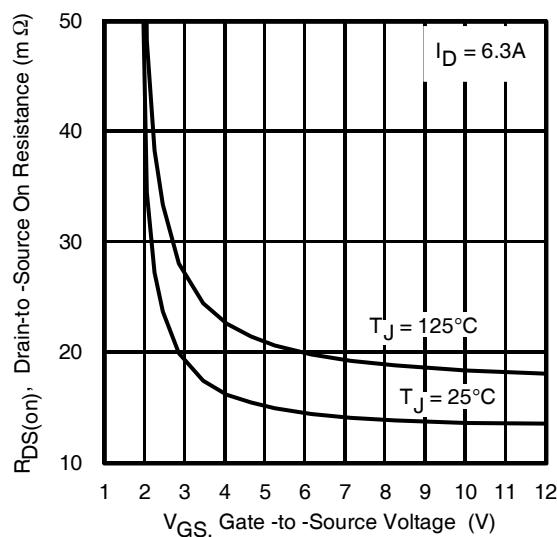
MOSFET (N-CHANNEL)


Fig 12. Typical On-Resistance vs. Gate Voltage

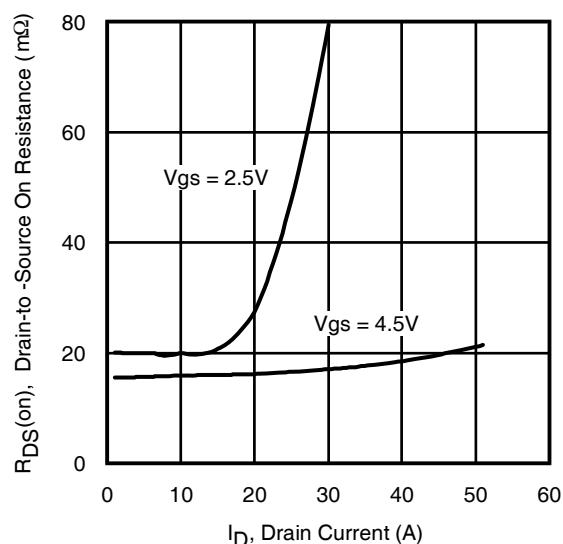


Fig 13. Typical On-Resistance vs. Drain Current

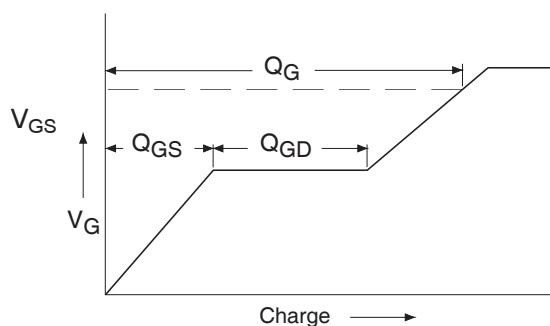


Fig 14a. Basic Gate Charge Waveform

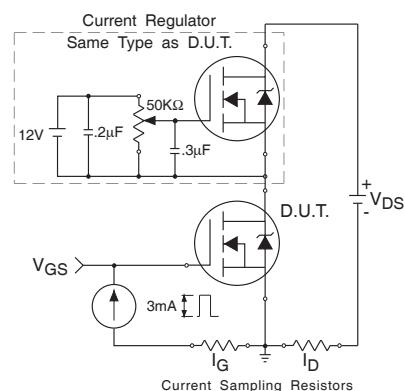


Fig 14b. Gate Charge Test Circuit

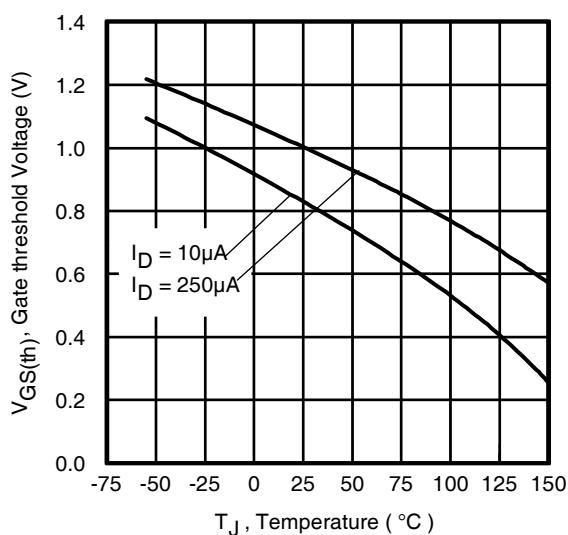


Fig 15. Typical Threshold Voltage vs. Junction Temperature

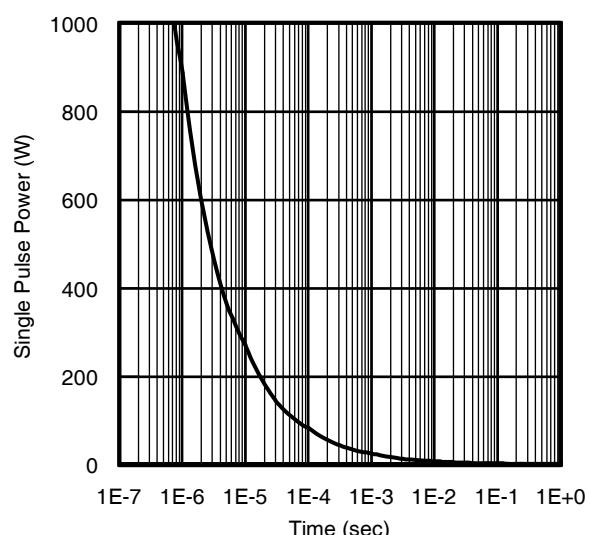
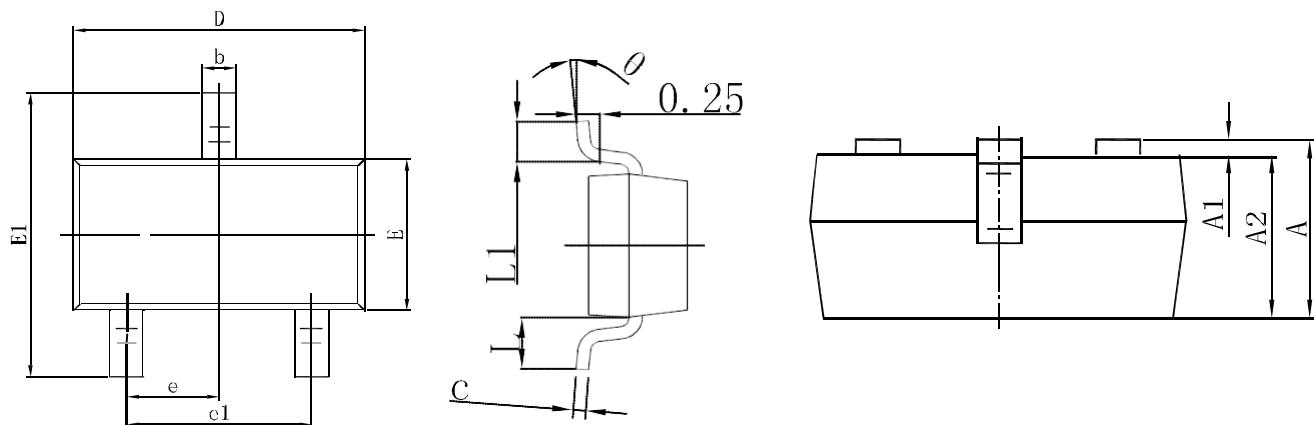
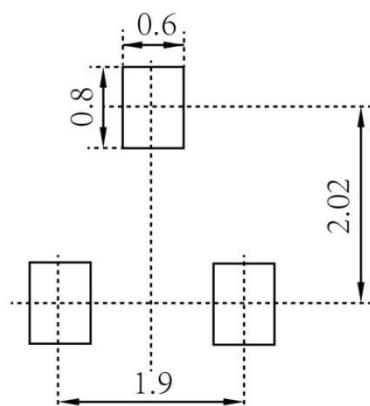


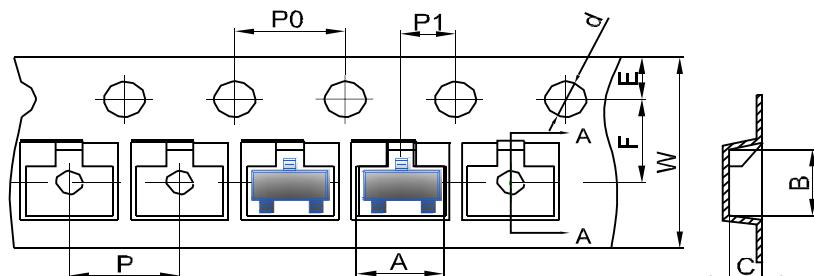
Fig 16. Typical Power vs. Time

MOSFET (N-CHANNEL)
SOT-23 Package Outline Dimensions


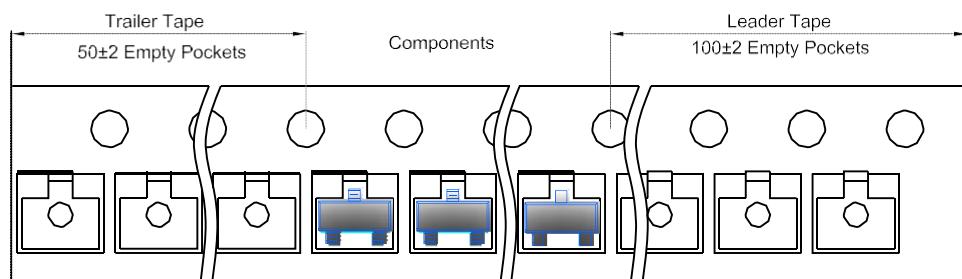
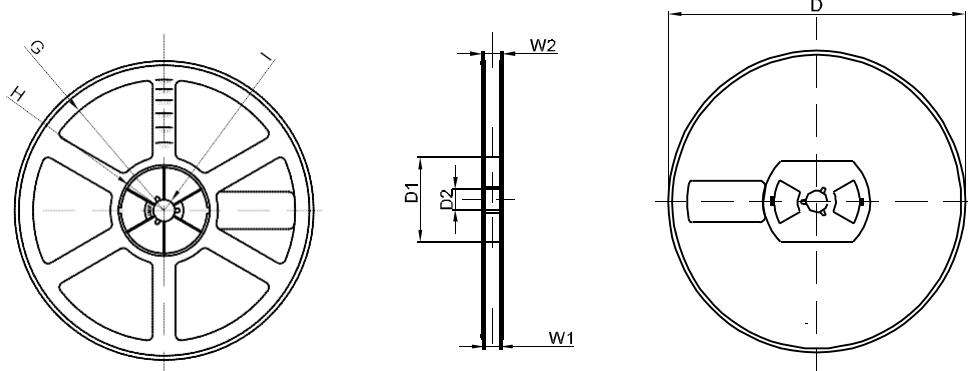
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	0.900	1.150	0.035	0.045
A1	0.000	0.100	0.000	0.004
A2	0.900	1.050	0.035	0.041
b	0.300	0.500	0.012	0.020
c	0.080	0.150	0.003	0.006
D	2.800	3.000	0.110	0.118
E	1.200	1.400	0.047	0.055
E1	2.250	2.550	0.089	0.100
e	0.950 TYP		0.037 TYP	
e1	1.800	2.000	0.071	0.079
L	0.550 REF		0.022 REF	
L1	0.300	0.500	0.012	0.020
θ	0°	8°	0°	8°

SOT-23 Suggested Pad Layout

Note:

1. Controlling dimension: in millimeters
2. General tolerance: $\pm 0.05\text{mm}$
3. The pad layout is for reference purposes only

MOSFET (N-CHANNEL)
SOT-23 Tape and Reel
SOT-23 Embossed Carrier Tape


TYPE	DIMENSIONS ARE IN MILLIMETER									
	A	B	C	d	E	F	P0	P	P1	W
SOT-23	3.15	2.77	1.22	Ø1.50	1.75	3.50	4.00	4.00	2.00	8.00
TOLERANCE	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1	±0.1

SOT-23 Tape Leader and Trailer

SOT-23 Reel


REEL OPTION	DIMENSIONS ARE IN MILLIMETER							
	D	D1	D2	G	H	I	W1	W2
7" DIA	Ø178	54.40	13.00	R78	R25.60	R6.50	9.50	12.30
TOLERANCE	±2	±1	±1	±1	±1	±1	±1	±1